Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.014”**

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**.014”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size = .007 x .007”**

**Backside Potential: CATHODE**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .014” X .014” DATE: 9/23/21**

**MFG: FAIRCHILD THICKNESS .008” P/N: BAT54**

**DG 10.1.2**

#### Rev B, 7/1